

## REMARKS

Applicants respectfully request reconsideration of this application as amended. Claims 1-3, 5-6, 8 and 10 have been amended. Claims 7, 9 and 11-31 have been cancelled without prejudice. No new claims have been added. Therefore, claims 1-6, 8 and 10 are presented for examination.

### 35 U.S.C. § 103 Rejections

Claims 1-5, 7, 11, 15, 17 and 30 stand rejected under 35 U.S.C. §103(a) as being anticipated over in view Hsieh, et al., U.S Patent No. 6,564,986, “(Hsieh)” in view of Stewart, U.S. Patent Publication No. 2003/0170450, (“Stewart”).

Applicants respectfully submit that Hsieh discloses “[a] *method for testing multiple IC packages* for solder joint fractures that occur in response to thermal cycling.” (Abstract; emphasis provided).

Stewart discloses “[a] *solid or semi-solid thermoplastic adhesive* adhered to a surface mount electronic device, an assembly made of at least a printed circuit board, a surface mount electronic device, solder joints providing a connection between the printed circuit board and the device, and solid thermoplastic adhesive joints attached to the device and the board.” (Abstract; emphasis provided).

In contrast, claim 1, in pertinent part, recites “attaching a printable circuit board (PCB) to the BGA package via the thermoplastic bonder on the perimeter of the BGA package and the array of solder balls with the thermoplastic bonder.” (emphasis provided). Hsieh discloses a solder joint fracture testing method; however, Hsieh fails to teach or reasonably suggest “attaching a printable circuit board (PCB) to the BGA package via the thermoplastic bonder on the perimeter of the BGA package and the array

of solder balls with the thermoplastic bonder” as recited by claim 1. (emphasis provided). Stewart discloses using thermoplastic adhesive with BGAs; however, Stewart does not teach or reasonably suggest that the thermoplastic bonder is on the perimeter of the BGA package. (claim 1). Applicants submit that neither Hsieh nor Stewart, individually or when combined, in any combination, teach or reasonably suggest “attaching a printable circuit board (PCB) to the BGA package via the thermoplastic bonder on the perimeter of the BGA package and the array of solder balls with the thermoplastic bonder” as recited by claim 1. (emphasis provided). Accordingly, Applicants respectfully request that the rejection of claim 1 and its dependent claims be withdrawn.

Claims 6, 8-10, 14, 18 and 31 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Hsieh and Stewart as applied to claims 1 and 11 above, and further in view of Austin, et al., U.S. Patent No. 6,284,173, (“Austin”).

Claims 6 and 8-10 depend from independent claim 1 and thus include all the limitations of their base claim. Claims 14, 18 and 31 have been cancelled, thus obviating the rejection. Accordingly, Applicants respectfully request that the rejection be withdrawn.

Claim 13 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Hsieh and Stewart as applied to claim 11 above, and further in view of Longgood, et al., U.S. Patent No. 6,045,032, (“Longgood”).

Claim 13 has been cancelled, thus obviating this rejection. Accordingly, Applicants respectfully request that the rejection be withdrawn.

### **Conclusion**

In light of the foregoing, reconsideration and allowance of the claims is hereby earnestly requested.

### **Invitation for a Telephone Interview**

The Examiner is requested to call the undersigned at (303) 740-1980 if there remains any issue with allowance of the case.

### **Request for an Extension of Time**

Applicants respectfully petition for an extension of time to respond to the outstanding Office Action pursuant to 37 C.F.R. § 1.136(a) should one be necessary. Please charge our Deposit Account No. 02-2666 to cover the necessary fee under 37 C.F.R. § 1.17(a) for such an extension.


### **Charge our Deposit Account**

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

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